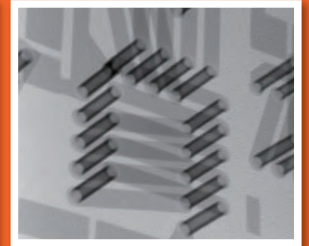


Glass substrate by **GWC** process



Glass
Wet
Cu plating



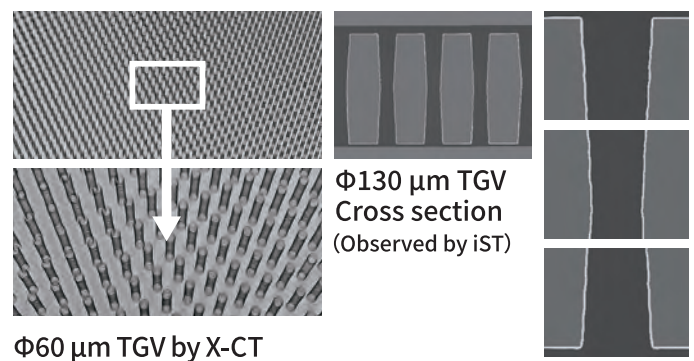
Features

- All Wet Process** without Sputtering, Sol-Gel process and Courting
- Direct Cu Plating on Glass** without Intermediate Layer (Ti, Cr etc.)
- Smooth and Transparency** without Glass Surface Etching
- Stable Adhesion Strength** Peel strength about 0.4 ~ 0.8 kN/m
- Excellent Cu film Uniformity inside TGV** Applicable to TGV until A.R. 20

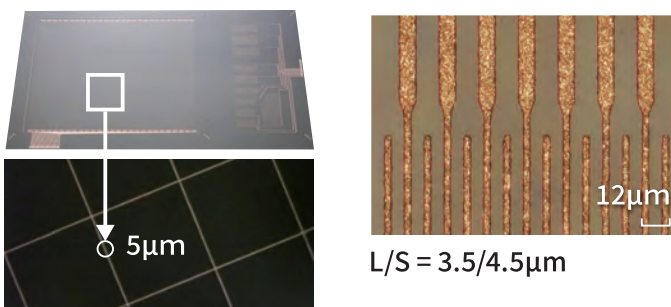
Peeling test Adhesion strength

Non Alkaline	0.8 kN/m
Borosilicate	0.5 kN/m
Quartz	0.4 kN/m

Cu uniformity inside TGV



Fine line formation



Touch sensor (L/S= 5μm/100μm)

Mass product accommodate size

Glass Type	Soda, Non-Alkaline Borosilicate, Quartz	
Shape, Size	Wafer	Φ 4, 6, 8, 12 inch
	Panel	≤515 ×510 mm (available in the near future)
TGV	Size	≥ Φ 5 μm (available in the near future)
	A.R.	≤20

